

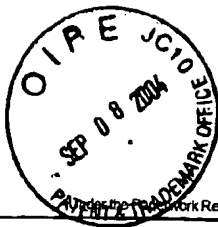


PTO/SB/08a/b (08-03)  
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<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (Use as many sheets as necessary)		<b>Complete If Known</b>			
		Application Number	09/866,463-Conf. #4951		
		Filing Date	May 24, 2001		
		First Named Inventor	Gregory J. Wilson		
		Art Unit	1742		
		Examiner Name	D. R. Valentine		
Sheet	1	of	2	Attorney Docket Number	291958157US3

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. <sup>1</sup>	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code <sup>2</sup> (if known)			

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	† <sup>4</sup>
		Country Code <sup>3</sup> -Number <sup>4</sup> -Kind Code <sup>5</sup> (if known)				
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Examiner Signature	Donald R Valentine			Date Considered	10/19/04	



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NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
<i>DN</i>		CONTOLINI ET AL., "Copper Electroplating Process for Sub-Half-Micron ULSI Structures," VMIC Conference 1995 ISMIC - 04/95/0322, pgs 322-328, June 17-29, 1995	
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<i>DN</i>		SINGER, P., "Copper Goes Mainstream: Low k to Follow," Semiconductor International, pgs 67-70, November 1997	

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Examiner Signature	<i>Donald R. Valentine</i>	Date Considered	10/19/04
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